



**Appendix 3 Product End-of-Life Disassembly instructions**

**Product Identification:**

Marketing Name / Model	Description
HP Compaq t5520, t5525, t5125, t5710	t5520 (800 MHz Windows XPe), t5525 (800 MHz Linux), t5125 (400 MHz Linux), t5710 (1.2 GHz Windows XPe)

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

**1.0 Items Requiring Selective Treatment**

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Qty of items in product.
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	Alkaline button style battery * 1
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB / PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		2
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		



## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips Screw drivers	Small and medium

## 3.0 Product Disassembly Process

<b>CMOS BATTERY</b>	
1	Remove the side access panel by removing the two black back panel screws from the I/O plate, and then removing the side access panel from the unit (see Figure 1 below).
2	Remove the chassis cover by removing the two screws from the back corner of the silver chassis, and then pulling the chassis cover off (see Figure 2 below).
3	Disconnect the speaker cable from the system board (see Figure 2 below).
4	After locating the battery on the system board, pull back on the clip that holds the battery in place, and then remove the battery (see Figure 3 below).
<b>SYSTEM BOARD</b>	
1	Remove the silver plastic piece from the top of the chassis (see Figure 4 below). NOTE: While this piece connects with tabs, you may have to break the tabs to remove it from the unit.
2	Remove the two screws that connect the heatpipe bracket to the top of the chassis (see Figure 5 below).
3	Remove the four screws that secure the system board to the chassis (see Figure 6 below).
4	Cut the two capacitors as shown in Figure 7 below.
5	Lift up the front of the system board, and then pull the board toward the front of the chassis until the ports on the back of the board are loose from the rear of the chassis. Lift the system board from the chassis.

3.1 Illustrations

FIGURE 1: Removing the side access panel



FIGURE 2: Removing the chassis cover and disconnecting the speaker

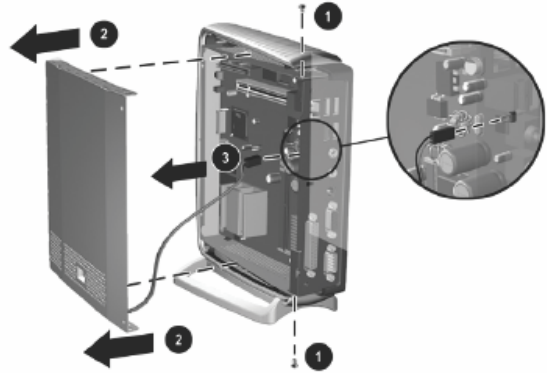


FIGURE 3: Removing the CMS battery

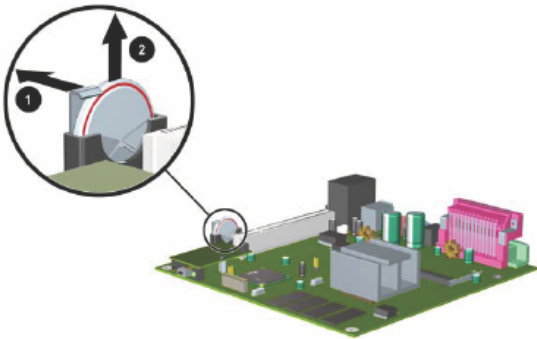


FIGURE 4: Top plastic piece to remove



FIGURE 5: Heatpipe bracket screw location

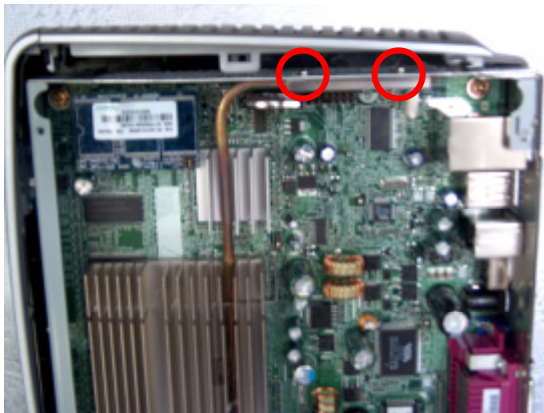


FIGURE 6: System board screw locations

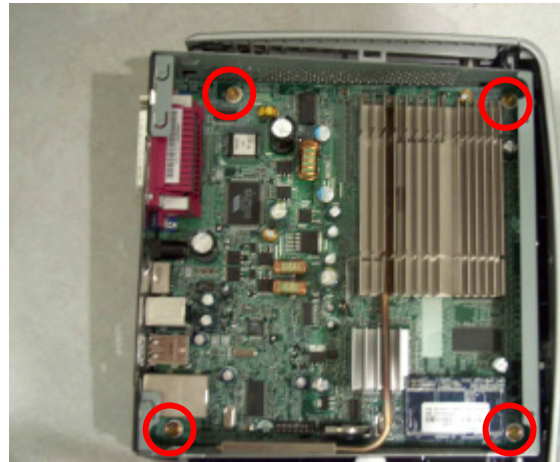


FIGURE 7: Cut capacitors

